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Process for Forming an Electrically Conductive Interconnect

Abstract of Disclosure

An electrically conductive metallic interconnect in a trench or via in a dielectric is provided by depositing a first liner layer on the walls and bottom of the trench or via; removing residual contamination from the bottom of the trench or via; depositing a second liner layer in the trench; depositing a seed layer and filling the trench with electrically conductive metallic material.